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Application No.: 10/670,190

Docket No.: 547-131

AMENDMENTS TO THE SPECIFICATION:

Please replace the paragraph on page 2, lines 3-13 with the following amended paragraph:

In German Patent Nos. DE197397197 and DE19739722, there is disclosed a conventional method of making the microstructure using circuit boards. The method comprises the steps of patterning the printed circuit boards and stacking the printed circuit boards one above the other to form fluid channel microstructures. Although the method proposed therein permits microstructure fabrication using batch processing techniques and at a relatively low cost, it is not suited for fabricating microstructures with high aspect ratios.

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